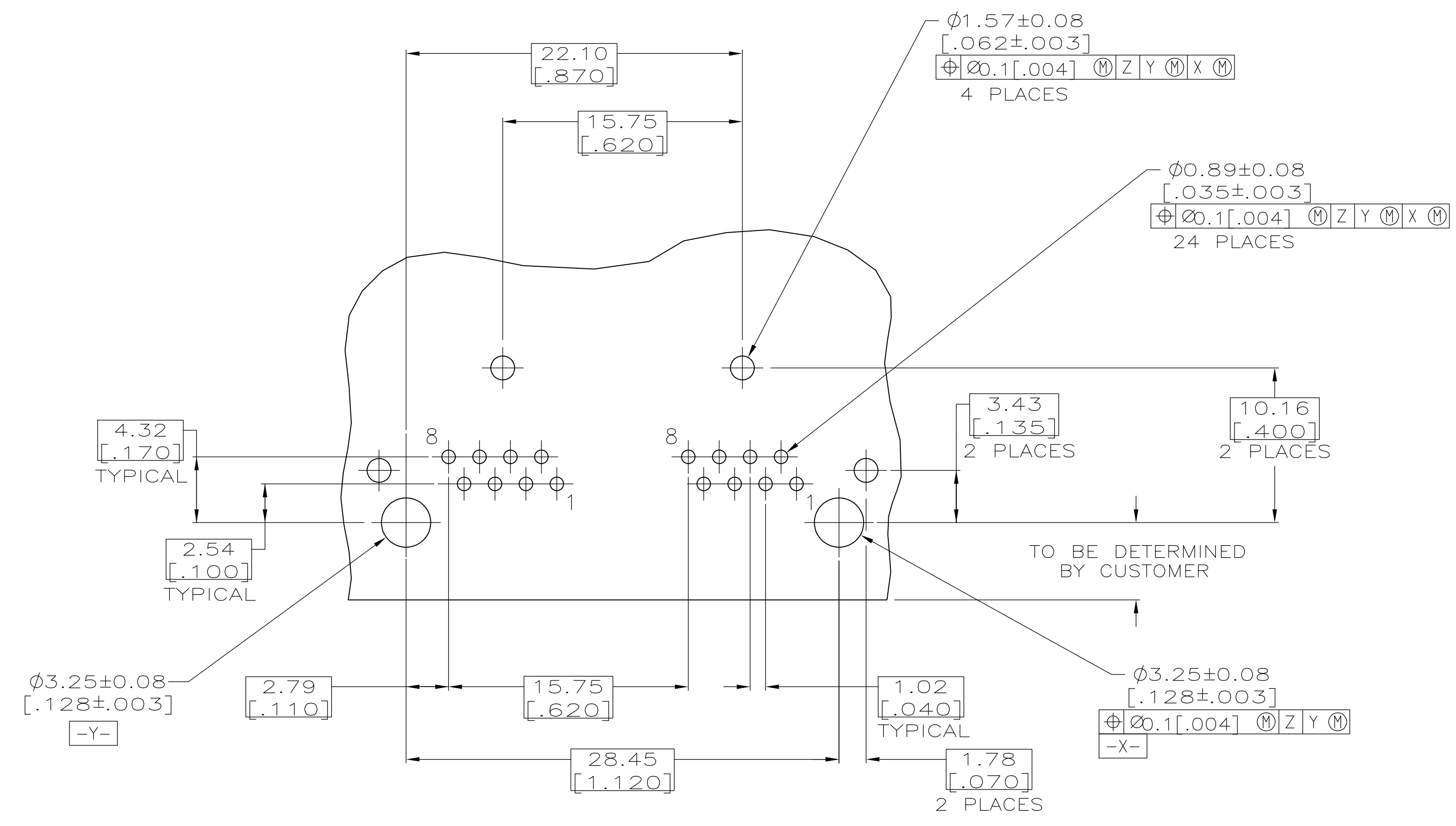


- MATERIAL: HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0; TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81μm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA. 1.27 μm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27 μm [.000050] MINIMUM THICK NICKEL. SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27 μm [.000050] MINIMUM SATIN NICKEL WITH 2.03 μm [.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- ³ SUGGESTED PANEL OPENING DIMENSIONS.
- ⁴ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- PARTS PACKAGED IN TAPE&REEL WITH DESICCANT.
- PARTS SUITABLE FOR LEAD FREE REFLOW PROCESSING TO 260° C



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)

1932389-1
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN D.ZHU 18JUN2009	Tyco Electronics Corporation	
DIMENSIONS: mm		CHK M.LI 18JUN2009	Shanghai 200233, P.R.China	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S.YAO 18JUN2009	NAME	
0 PLC ± -		PRODUCT SPEC		
1 PLC ± -		108-1163-4		
2 PLC ± 0.25(.01)		APPLICATION SPEC		
3 PLC ± 0.13(.005)		114-2154		
4 PLC ± -		RESTRICTED TO		
ANGLES ± -		SIZE CASE CODE DRAWING NO		
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	WEIGHT		A1 00779 C=1932389
		CUSTOMER DRAWING		SCALE 4:1 SHEET 1 OF 1 REV A2